

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A semiconductor device, comprising:
a base substrate including a base wiring pattern;
a first circuit substrate disposed over the base substrate and including a first wiring pattern;
a first semiconductor element mounted on the first circuit substrate and including a first electrode electrically connected to the first wiring pattern;
a second circuit substrate disposed over the first circuit substrate and including a second wiring pattern;
a second semiconductor element mounted on the second circuit substrate and including a second electrode electrically connected to the second wiring pattern;
a first protruded electrode electrically connected to the first wiring pattern and provided protruding from the first circuit substrate and bonded to the base wiring pattern; and
a second protruded electrode electrically connected to the second wiring pattern and provided protruding from the second circuit substrate and bonded to the base wiring pattern.
2. (Original) The semiconductor device according to claim 1, further comprising a third semiconductor element mounted on the base substrate and including a third electrode electrically connected to the base wiring pattern.
3. (Original) The semiconductor device according to claim 1, wherein the second protruded electrode is thicker than the first protruded electrode.
4. (Original) The semiconductor device according to claim 1, further comprising another semiconductor element layered on the first semiconductor element.

5. (Original) The semiconductor device according to claim 1, further comprising another semiconductor element layered on the second semiconductor element.

6-7. (Canceled).

8. (Currently amended) An electronic device comprising a semiconductor device recited in ~~any one of~~ claim 1.

9. (Original) The semiconductor device according to claim 1, wherein the base substrate is equipped with a dielectric substrate material.

10. (Original) The semiconductor device according to claim 1, wherein the base wiring pattern has a multiple layered wiring structure.

11. (Original) The semiconductor device according to claim 1, wherein the second semiconductor element includes electrodes.

12. (Original) The semiconductor device according to claim 1, wherein the base wiring pattern includes lands bonded to the first and second protruded electrodes.

13. (Original) The semiconductor device according to claim 1, wherein the first and second protruded electrodes are bonded to the base wiring pattern selected from the group consisting of anisotropic conductive adhesive, dielectric adhesive, alloy bonding, metal bonding and inter-metal diffusion bonding.

14. (Original) The semiconductor device according to claim 11, wherein the electrodes are formed from electrode pads.

15. (Original) The semiconductor device according to claim 11, wherein the electrodes of the second semiconductor element are electrically connected to the second wiring pattern by a face-down bonding method.

16. (Original) The semiconductor device according to claim 11, wherein the electrodes of the second semiconductor element are electrically connected to the second wiring pattern by a wire-binding method.

17. (Original) The semiconductor device according to claim 1, wherein the protruded electrodes are formed from a conductive member.

18. (Original) The semiconductor device according to claim 17, wherein the conductive member includes a structure in which a plurality of conductive films are stacked in layers.

19. (Original) The semiconductor device according to claim 17, wherein the conductive member is selected from the group consisting of a metal, a metal compound, an alloy, a conductive paste and a solder metal.

20. (Original) A semiconductor device, comprising:
a base substrate including a base wiring pattern;
a first circuit substrate disposed over the base substrate and including a first wiring pattern;
a first semiconductor element mounted on the first circuit substrate and including a first electrode electrically connected to the first wiring pattern;
a second circuit substrate disposed over the first circuit substrate and including a second wiring pattern;
a second semiconductor element mounted on the second circuit substrate and including a second electrode electrically connected to the second wiring pattern; and
means for electrically connecting to the first and second wiring patterns, protruding from the first and second circuit substrates and bonding to the base wiring pattern.